

# FSUSB63 — 3:1 High-Speed USB 2.0 Switch / Multiplexer

### **Features**

Curitab Tuna	2.4 LICD Curitob
Sw itch Type	3:1 USB Switch
LIOD	USB 2.0 High-Speed &
USB	Full-Speed Compliant
Break-Before-Make Time	126µs
Ron	6Ω Typical
Con	6pF Typical
Bandw idth	830MHz
Vcc	2.7 to 4.4V
V <sub>CNTRL</sub>	0 to V <sub>CC</sub>
Operating Temperature	-40°C to 85°C
ICCSLP	<1µA
ССАСТ	7.5µA Typical
Package	12- Lead UMLP 1.80 x 1.80 x
rackaye	0.55mm, 0.40mm pitch
Top Mark	KG
Ordering Information	FSUSB63UMX

## **Applications**

- Cell Phone, Digital Camera, Notebook
- LCD Monitor, TV, and Set-Top Box
- Netbook, Mobile Internet Device (MID)

### **Description**

The FSUSB63 is a bi-directional, low-power, High-Speed (HS) USB 2.0 3:1 Multiplexer (MUX). It is optimized for switching among three high-speed (480Mbps) sources or any combination of high-speed and full-speed (12Mbps) USB sources, such as an application processor, to one USB 2.0 connector.

The FSUSB63 has a break-before-make time to force reenumeration by the host when switching between different HS USB 2.0 controllers and thus requires minimal software changes.

The FSUSB63 is compliant with the requirements of USB 2.0 and features extremely low on capacitance  $(C_{ON})$ . The wide bandwidth exceeds the requirement to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

## **Typical Application**

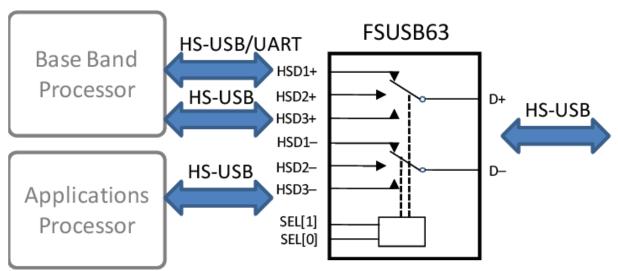


Figure 1. Analog Symbol

# **Pin Configuration**

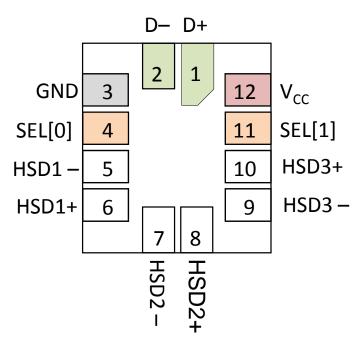


Figure 2. Pin Assignments (Top Through View)

## **Pin Descriptions**

Pin #	Name	Description
1	D+	USB 2.0 High Speed or Full Speed Data Bus D+
2	D-	USB 2.0 High Speed or Full Speed Data Bus D-
3	GND	Ground
4	SEL[0]	Path Selection Control Inputs (see functional table below)
5	HSD1-	Multiplexed First Source Path for D-
6	HSD1+	Multiplexed First Source Path for D+
7	HSD2-	Multiplexed Second Source Pathfor D-
8	HSD2+	Multiplexed Second Source Pathfor D+
9	HSD3-	Multiplexed Third Source Path for D-
10	HSD3+	Multiplexed Third Source Path for D+
11	SEL[1]	Path Selection Control Inputs (see functional table below)
12	Vcc	Supply Voltage

## **Functional Table**

Mode	SEL[1]	SEL[0]	Function
Sleep Mode	0	0	D+, D- Switch PathsOpen
USB Port 1	0	1	D+=HSD1+, D-=HSD1-
USB Port 2	1	0	D+=HSD2+, D-=HSD2-
USB Port 3	1	1	D+=HSD3+, D-=HSD3-

# **Eye Compliance**

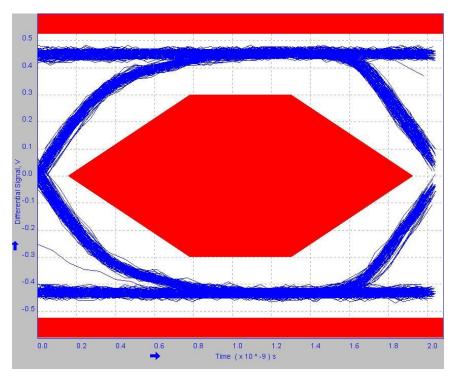


Figure 3. USB 2.0 HS-USB Eye Compliance Pass Through (without Switch)

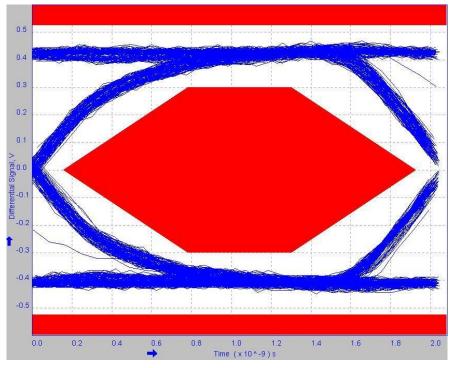


Figure 4. USB 2.0 HS-USB Eye Compliance with Switch

### Notes:

- 1. Figure 3 indicates the HS-USB eye compliance of the source across a characterization board proir to the implementation of the sw tich.
- 2. Figure 4 shows the total impact the swich has on HS-USB eye compliance when compared to Figure 3

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
Vcc	Supply Voltage		-0.50	5.25	V
V <sub>CNTRL</sub>	DC Input Voltage (SEL[1:0]) <sup>(3)</sup>		-0.5	Vcc	V
Vsw	DC Sw itch I/O Voltage <sup>(3)</sup>		-0.50	5.25	V
l <sub>IK</sub>	DC Input Diode Current		-50		mA
Юит	DC Switch Current			50	mA
T <sub>STG</sub>	Storage Temperature	-65	+150	°C	
MSL	Moisture Sensitivity Level (JEDEC J-STD-020A)	Moisture Sensitivity Level (JEDEC J-STD-020A)		1	Level
	IEC61000-4-2 System on USB Connector Pins	Air Gap	15.0		
	D+ & D-	Contact	8.0		1
ESD		Power to GND	16.0		kV
EOD	Human Body Model, JEDEC: JESD22-A114		5.0		KV
		All Pins	5.0		
	Charged Device Model, JEDEC: JESD22-C101	1	1.5		1

#### Note:

3. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. ON Semiconductor does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
V <sub>CC</sub>	Supply Voltage	2.7	4.4	V
V <sub>CNTRL</sub> <sup>(4)</sup>	Control Input Voltage (SEL[1:0])	0	Vcc	V
V <sub>SW</sub>	Sw itch I/O Voltage	-0.5	4.3	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

### Note:

4. The control input must be held HIGH or LOW and it must not float.

### **DC Electrical Characteristics**

All typical values are for  $V_{CC}$ =3.3V at  $T_A$ =25°C unless otherwise specified.

Symbol	Parameter	Conditions	V (V)	T <sub>A</sub> =- 40°C to +85°C			Units
Symbol		Conditions	V <sub>CC</sub> (V)	Min.	Тур.	Max.	Units
$V_{IK}$	Clamp Diode Voltage	I <sub>IN</sub> =-18mA	2.7			-1.2	V
$V_{IH}$	Input Voltage High	SEL[1], SEL[0] Inputs	2.7 to 4.3	1.0			V
$V_{IL}$	Input Voltage Low	SEL[1], SEL[0] Inputs	2.7 to 4.3			0.35	V
I <sub>IN</sub>	Control Input Leakage	All Combinations of SEL[1] & SEL[0] in the Truth Table (LOW=0V & HIGH= $V_{CC}$ )	4.3			1	μΑ
l <sub>oz</sub>	Off-State Leakage	$0 \le \square D_n$ , $HSD1_n$ , $HSD2_n$ , $HSD3_n \le \square 3.6V$	4.3	-2		2	μΑ
I <sub>OFF</sub>	Power-Off Leakage Current (All I/O Ports)	$V_{SW}$ =0V to 4.3V, $V_{CC}$ =0V, Figure 7	0	-2		2	μΑ
R <sub>ON</sub> <sup>(5)</sup>	HS Switch On Resistance	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA, Figure 6	3.0		6.0	7.8	Ω
$\Delta R_{\text{ON}}$	HS Delta R <sub>ON</sub> <sup>(6)</sup>	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA	3.0		0.50		Ω
I <sub>CCSLP</sub>	Sleep Mode Supply Current	SEL[1]=SEL[0]=0	3.6			1	μΑ
	Active Made Cupply Current	V <sub>CNTRL</sub> =0 or V <sub>CC</sub> ,	2.7		7.5	15.0	μΑ
ICCACT	Active Mode Supply Current	I <sub>OUT</sub> =0	3.6		8.5	16.0	μΑ
1	Increase in I <sub>CC</sub> Current per Control Input	V <sub>CNTRL</sub> =1.8V	3.6		1.5	4.0	μΑ
I <sub>CCT</sub>	and V <sub>CC</sub>	V <sub>CNTRL</sub> =1.2V	3.6		3.0	5.0	μΑ

#### Notes

- 5. Measured by the voltage drop between HSD<sub>n</sub> and D<sub>n</sub> pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSD<sub>n</sub> or D<sub>n</sub> ports).
- 6. Guaranteed by characterization.

### **AC Electrical Characteristics**

All typical values are for V<sub>CC</sub>=3.3V at T<sub>A</sub>=25°C unless otherwise specified.

Symbol	Parameter	Conditions	V (V)	T <sub>A</sub> =- 40°C to +85°C			Units
Symbol			V <sub>CC</sub> (V)	Min.	Тур.	Max.	Units
ton	Turn-On Time when Switching from One USB Path (or Disabled i.e. SEL=00) to Another USB Path	$R_L$ =50 $\Omega$ , $C_L$ =35pF $V_{sw}$ =0.8V Figure 8, Figure 9	3.0 to 3.6	126		400	μs
t <sub>OFF</sub>	Tum-Off Time SEL≠00 (Any of the Three USB Paths Active) to SEL=00 (Disabled)	$R_L$ =50 $\Omega$ , $C_L$ =35pF $V_{sw}$ = 0.8 $V$ Figure 8, Figure 9	3.0 to 3.6			45	ns
t <sub>PD</sub>	Propagation Delay <sup>(7)</sup>	$C_L$ =5pF, $R_L$ =50 $\Omega$ Figure 8, Figure 10	3.3		0.25		ns
t <sub>BBM</sub>	Break-Before-Make Time	$R_L$ =50 $\Omega$ , $C_L$ =35pF $V_{SW1}$ = $V_{SW2}$ = 0.8V, Figure 12	3.0 to 3.6	126		400	μs
O <sub>IRR</sub>	Off Isolation <sup>(7)</sup>	R <sub>L</sub> =50Ω, f=240MHz Figure 14	3.0 to 3.6		-42		dB
Xtalk	Non-Adjacent Channel Crosstalk <sup>(7)</sup>	R <sub>L</sub> =50Ω, f=240MHz Figure 15	3.0 to 3.6		-33		dB
BW	-3db Bandwidth <sup>(7)</sup>	$R_L$ =50 $\Omega$ , $C_L$ =0pF Figure 13	3.0 to 3.6		830		MHz
D11	Sub Bandwidth	$R_L$ =50 $\Omega$ , $C_L$ =5pF Figure 13	3.0 to 3.6		510		MHz

### Note:

7. Guaranteed by characterization.

# **USB High-Speed Related AC Electrical Characteristics**

Symbol	Parameter	Conditions Vcc (V)		TA=-	40°C to	+85°C	Units
Syllibol	Farameter	Conditions	VCC (V)	Min.	Тур.	Max.	Uiils
t <sub>SK(P)</sub>	Pulse Skew (8)	$V_{SW}$ =0.2 $V$ diff <sub>PP</sub> , Figure 11, $C_L$ =5 $pF$	3.0 to 3.6		10		ps
t <sub>SK(I)</sub>	Skew Between Differential Signals within a Pair (8)	V <sub>SW</sub> =0.2Vdiff <sub>PP</sub> , Figure 11, C <sub>L</sub> =5pF	3.0 to 3.6		10		ps

# Capacitance

Symbol	Parameter	Conditions	T <sub>A</sub> =- 40°C to +85°C			Units
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
C <sub>iN</sub>	SEL[1:0] Input Capacitance <sup>(8)</sup>	Vcc=0V		3		
Con	Con D+/D- On Capacitance <sup>(8)</sup>	V <sub>CC</sub> =3.3V, Any of the Three Switch Paths Enabled, f=1MHz, Figure 17		6		, F
JON	On Supasitance	V <sub>CC</sub> =3.3V, Any of the Three Sw itch Paths Enabled, f=240MHz <sup>(9)</sup>		5		pF
Coff	HSD1 <sub>n</sub> , HSD2 <sub>n</sub> , HSD3 <sub>n</sub> Off Capacitance <sup>(8)</sup>	V <sub>CC</sub> =0V or (V <sub>CC</sub> =3.3V and SEL[1]=SEL[0]=0V) Figure 16		2		

### Notes:

- 8. Guaranteed by characterization.
- 9. Effective capacitance measured on a network analyzer.

## **Reference Schematic**

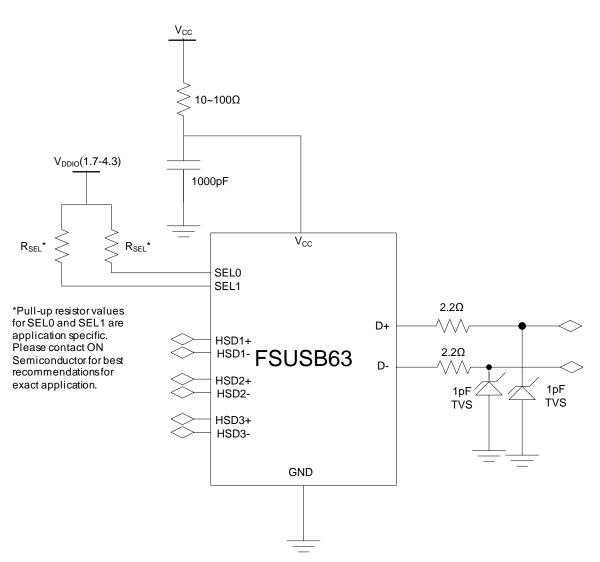


Figure 5. Reference Schematic

## **Test Diagrams**

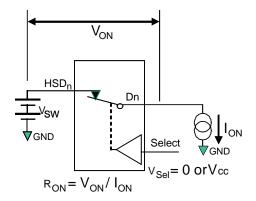
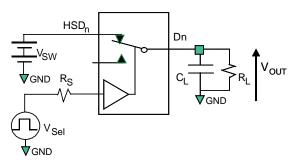


Figure 6. On Resistance



 $R_L$ ,  $R_S$ , and  $C_L$  are functions of the application environment (see AC Tables for specific values)  $C_L$  includes test fixture and stray capacitance.

Figure 8. AC Test Circuit Load

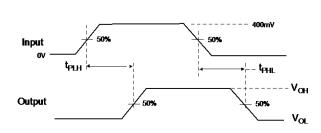
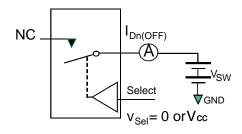


Figure 10. Propagation Delay (t<sub>R</sub>t<sub>F</sub> - 500ps)



\*\*Each switch port is tested separately

Figure 7. Off Leakage

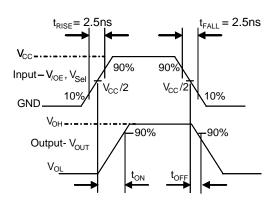


Figure 9. Turn-On / Turn-Off Waveforms

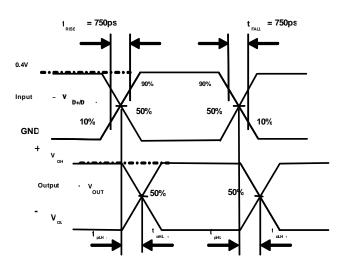


Figure 11. Skew Test Waveforms tsk(P)=| tpLH- - tpHL- | or | tpLH+ - tpHL+ | tsk(I)=| tpLH- - tpHL+ | or | tpLH+ - tpHL- |

## Test Diagrams (Continued)

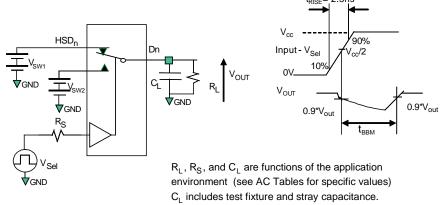


Figure 12. Break-Before-Make Interval Timing

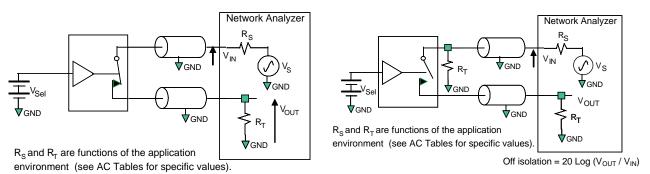


Figure 13. Bandwidth

Figure 14. Channel Off Isolation

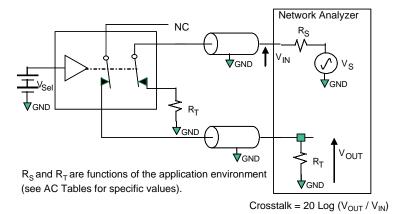


Figure 15. Non-Adjacent Channel-to-Channel Crosstalk

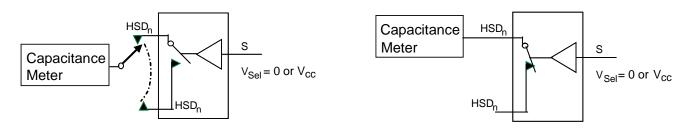
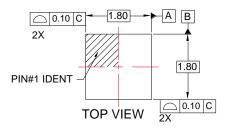
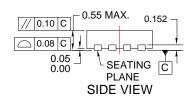


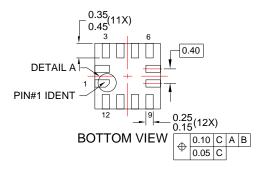
Figure 16. Channel Off Capacitance

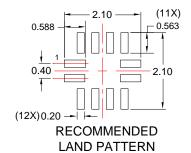
Figure 17. Channel On Capacitance

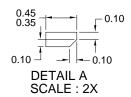
## **Physical Dimensions**











### NOTES:

- A. PACKAGE DOES NOT FULLY CONFORM TO JEDEC STANDARD.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M. 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
- E. DRAWING FILENAME: MKT-UMLP12Arev4.



Figure 18. 12-Lead, Ultrathin Molded Leadless Package (UMLP)

### Ordering Information

Part Number	Top Mark	Operating Temperature Range	Package
FSUSB63UMX	KG		12-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.8mm x 1.8mm x 0.55mm, 0.4mm pitch

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